



## Material Content Data Sheet



<b>Sales Product Name</b>		SAK-XC2287-96F80L AC		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001071458						
<b>Package</b>		PG-LQFP-144-4		<b>Weight*</b>		1461.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	40.856	2.80	2.80	27955	27955
leadframe	inorganic material	phosphorus	7723-14-0	0.122	0.01		84	
	non noble metal	zinc	7440-66-6	0.489	0.03		335	
	non noble metal	iron	7439-89-6	9.785	0.67		6695	
wire	non noble metal	copper	7440-50-8	397.309	27.19	27.90	271852	278966
	noble metal	gold	7440-57-5	5.975	0.41	0.41	4088	4088
	encapsulation	organic material	carbon black	1333-86-4	4.921	0.34		3367
plastics	plastics	epoxy resin	-	132.873	9.09		90916	
	inorganic material	silicondioxide	60676-86-0	846.452	57.91	67.34	579172	673455
leadfinish	non noble metal	tin	7440-31-5	9.120	0.62	0.62	6240	6240
plating	noble metal	silver	7440-22-4	3.110	0.21	0.21	2128	2128
glue	plastics	epoxy resin	-	2.619	0.18		1792	
	noble metal	silver	7440-22-4	7.858	0.54	0.72	5376	7168
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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